Title (en)

METHOD FOR GROWING THIN SEMICONDUCTOR RIBBONS

Title (de)

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Title (fr)

PROCEDE DE TIRAGE DE RUBANS DE SEMI-CONDUCTEUR DE FAIBLE EPAISSEUR

Publication

EP 1871926 A1 20080102 (FR)

Application

EP 06726209 A 20060301

Priority

- FR 2006050185 W 20060301
- FR 0551032 A 20050422

Abstract (en)

[origin: WO2006111668A1] The invention relates to a method for growing at least one ribbon made of a semiconductor material (40-42) according to which two parallel and interspaced filaments (24-26) vertically pass through, upward and at a continuous speed, the surface of a bath of this molten semiconductor material, the ribbon (40-42) being formed from a meniscus located between the filaments and essentially at the level of said surface. According to the invention, a supporting strip (22) is placed between the filaments (24-26), the supporting strip (22) vertically passing through, upward and at a continuous speed, the surface of the molten semiconductor material at the same speed as the filaments, the semiconductor ribbon (40-42) thus being formed on one of the two sides of the supporting strip and being supported by this side. The invention serves to produce polycrystalline silicon ribbons for manufacturing photovoltaic cells.

IPC 8 full level

C30B 15/00 (2006.01); **C30B 15/24** (2006.01); **C30B 29/06** (2006.01)

CPC (source: EP US)

C30B 15/22 (2013.01 - EP US); **C30B 15/34** (2013.01 - EP US); **C30B 29/06** (2013.01 - EP US); **C30B 29/08** (2013.01 - EP US); **C30B 29/42** (2013.01 - EP US); **H01L 31/18** (2013.01 - EP US)

Citation (search report)

See references of WO 2006111668A1

Designated contracting state (EPC)

AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HU IE IS IT LI LT LU LV MC NL PL PT RO SE SI SK TR

DOCDB simple family (publication)

WO 2006111668 A1 20061026; AU 2006238527 A1 20061026; CN 101128625 A 20080220; EP 1871926 A1 20080102; FR 2884834 A1 20061027; FR 2884834 B1 20070608; JP 2008536793 A 20080911; US 2009050051 A1 20090226

DOCDB simple family (application)

FR 2006050185 W 20060301; AU 2006238527 A 20060301; CN 200680005915 A 20060301; EP 06726209 A 20060301; FR 0551032 A 20050422; JP 2008507134 A 20060301; US 88424206 A 20060301